

ON Semiconductor®

FQA13N50C-F109

N-Channel QFET® MOSFET

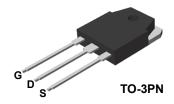
500 V, 13.5 A, 480 m Ω

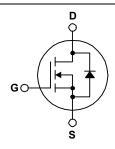
Description

These N-Channel enhancement mode power field effect transistors are produced using ON Semiconductor's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction, electronic lamp ballasts based on half bridge topology.

Features

- 13.5 A, 500 V, $R_{DS(on)}$ = 480 m Ω (Max.) @ V_{GS} = 10 V, I_D = 6.75 A
- Low Gate Charge (Typ. 43 nC)
- Low Crss (Typ. 20 pF)
- 100% Avalanche Tested
- · Improved dv/dt Capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQA13N50C-F109	Unit
V_{DSS}	Drain-Source Voltage		500	V
I _D	Drain Current - Continuous (T _C = 25°C)		13.5	Α
	- Continuous (T _C = 100°C)		8.5	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	54	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	860	mJ
I _{AR}	Avalanche Current	(Note 1)	13.5	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	21.8	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P_{D}	Power Dissipation (T _C = 25°C)		218	W
	- Derate above 25°C		1.56	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds.		300	°C

Thermal Characteristics

Symbol	Parameter	FQA13N50C-F109	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.58	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA13N50C-F109	FQA13N50C	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	500			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.5		V/°C
I _{DSS}	Zoro Cata Valtago Drain Current	V _{DS} = 500 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 400 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	-		100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 6.75 A		0.39	0.48	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 6.75 \text{ A}$		15	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,	 1580	2055	pF
Coss	Output Capacitance	f = 1.0 MHz	 180	235	pF
C _{rss}	Reverse Transfer Capacitance		 20	25	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 250 V, I _D = 13.5 A,	 25	60	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	 100	210	ns
t _{d(off)}	Turn-Off Delay Time	1.19	 130	270	ns
t _f	Turn-Off Fall Time	(Note 4)	 100	210	ns
Qg	Total Gate Charge	V _{DS} = 400 V, I _D = 13.5 A,	 43	56	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	 7.5		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	 18.5		nC

Drain-Source Diode Characteristics and Maximum Ratings

Maximum Continuous Drain-Source Diode Forward Current				13	Α
Maximum Pulsed Drain-Source Diode Forward Current				52	Α
Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 13.5 \text{ A}$			1.4	٧
Reverse Recovery Time	V _{GS} = 0 V, I _S = 13.5 A,		410		ns
Reverse Recovery Charge	dI _F / dt = 100 A/μs		4.5		μC
	Maximum Pulsed Drain-Source Diode F Drain-Source Diode Forward Voltage Reverse Recovery Time	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$			

- 1. Repetitive rating : pulse-width limited by maximum junction temperature.
- 2. L = 5.6 mH, I_{AS} = 13.5 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. I_{SD} ≤ 13.5 A, di/dt ≤ 200 A/ μ s, V_{DD} ≤ BV $_{DSS}$, starting T_{J} = 25°C.
- 4. Essentially independent of operating temperature

Typical Characteristics

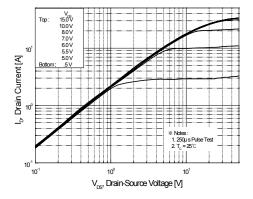


Figure 1. On-Region Characteristics

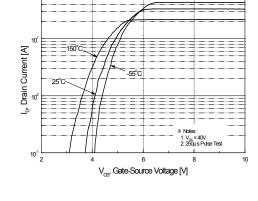


Figure 2. Transfer Characteristics

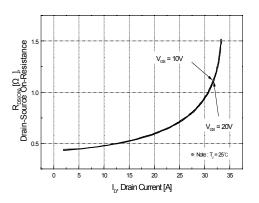


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

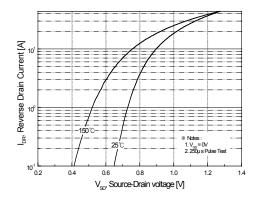


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

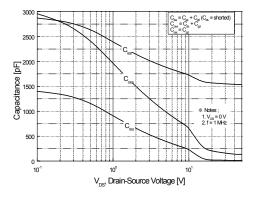


Figure 5. Capacitance Characteristics

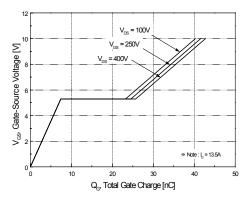


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

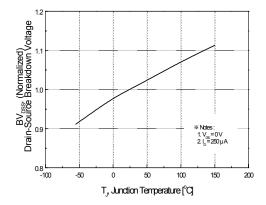


Figure 7. Breakdown Voltage Variation vs Temperature

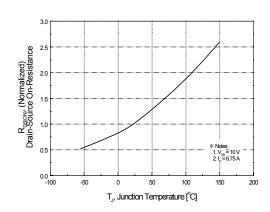


Figure 8. On-Resistance Variation vs Temperature

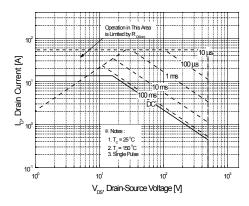


Figure 9. Maximum Safe Operating Area

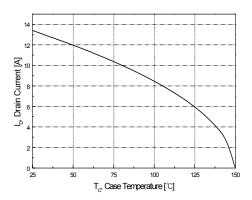


Figure 10. Maximum Drain Current vs Case Temperature

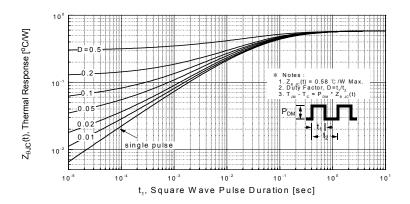


Figure 11. Transient Thermal Response Curve for FQA13N50C

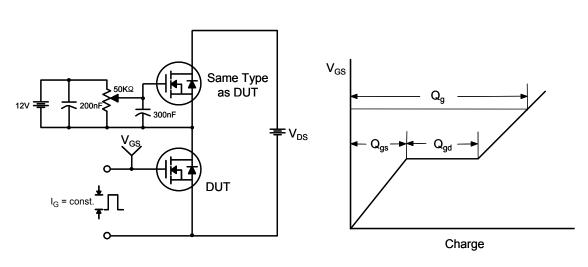


Figure 12. Gate Charge Test Circuit & Waveform

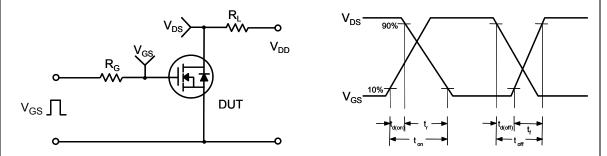


Figure 13. Resistive Switching Test Circuit & Waveforms

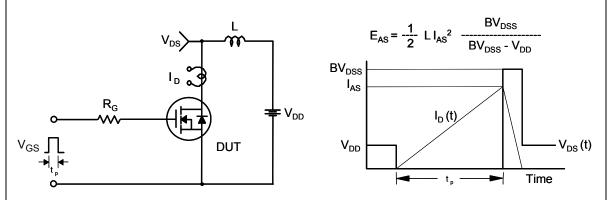
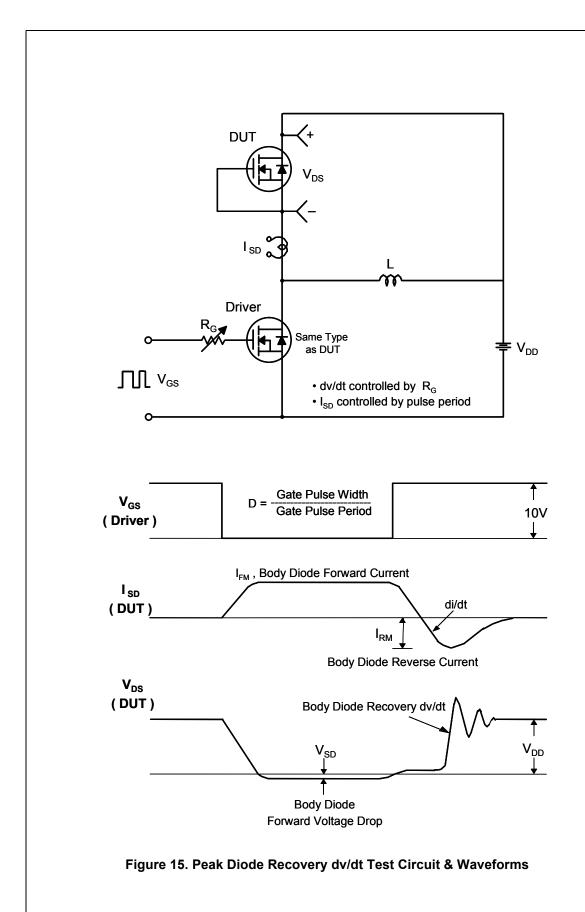
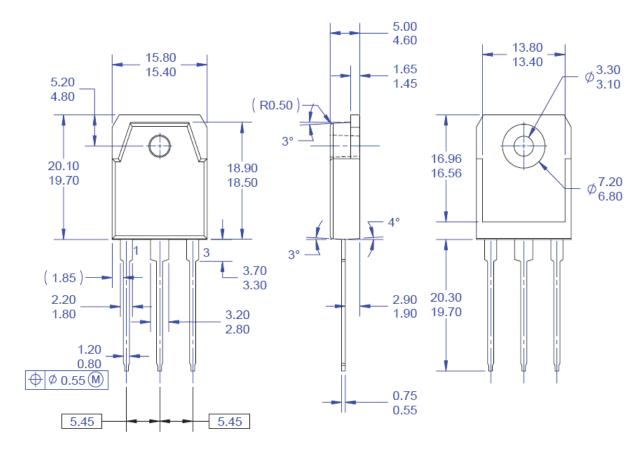


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions



(R0.50)

NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
- E) THIS PACKAGE IS INTENDED ONLY FOR TO3PN.
- F) DRAWING FILE NAME: TO3P03AREV4.

Figure 16. TO3, 3-Lead, Plastic, EIAJ SC-65

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